

Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1. (Currently Amended) An electroless copper plating solution, ~~containing~~consisting essentially of a copper ion source, a water-soluble nitrogen-containing polymer and glyoxylic acid and phosphinic acid as reducing agents in the electroless copper plating solution, wherein the concentration of the water-soluble nitrogen-containing polymer is 0.0001-5 g/L, the concentration of glyoxylic acid is 0.005-0.5 mol/L and the concentration of phosphinic acid is 0.001-0.5 mol/L.

2. (Original) An electroless copper plating solution according to Claim 1, wherein the water-soluble nitrogen-containing polymer is a polyacrylamide or a polyethyleneimine.

3. (Previously Presented) An electroless copper plating solution according to Claim 1, wherein a weight average molecular weight (Mw) of the water-soluble nitrogen-containing polymer is at least 100,000, and Mw/Mn (Mn is a number average molecular weight thereof) is 10.0 or less.

4. (Canceled)

5. (Previously Presented) In an electroless copper plating method for depositing a copper plating on a substrate, the improvement comprising performing the electroless copper plating with the electroless copper plating solution according to Claim 1.

6. (Previously Presented) An electroless copper plating solution, containing a polyacrylamide and glyoxylic

acid and phosphinic acid as reducing agents in the electroless copper plating solution.

7. (Previously Presented) An electroless copper plating solution, containing a polyethyleneimine and glyoxylic acid and phosphinic acid as reducing agents in the electroless copper plating solution.

8. (Previously Presented) An electroless copper plating solution according to Claim 1, wherein copper sulfate is used as a copper source.

9. (Previously Presented) An electroless copper plating solution according to Claim 8, additionally comprising ethylenediaminetetraacetate.